WHAT IS CLAIMED IS:

1. An electronic device(101;201;301), comprising:

a flexible display(261;361) comprising a first area(261a;361a) and a second area(261b;361b);

a first housing(210;310) supporting the first area of the flexible display;

a second housing(220;320) supporting the second area of the flexible display;

a hinge structure(234;334) rotatably connecting the first housing and the second housing;

a first bracket(231;331) disposed in the first housing and having a first opening(331a);

a second bracket(232;332) disposed in the second housing and having a second opening(332a); and

a flexible printed circuit board (FPCB)(290;390) extending from a first space(210a;310a) formed by the first housing to a second space(220a;320a) formed by the second housing across the hinge structure, and formed in a multi-layer structure,

wherein the FPCB comprises a first sealing portion(3900a) disposed in the first opening, a second sealing portion(3900b) disposed in the second opening and, flexible portions(3903a, 3903b) connected to each of the first sealing portion and the second sealing portion and extending toward the hinge structure, and

wherein at least one stepped space(396) is formed between a plurality of layers of the flexible portion of the FPCB and, at least one waterproof member(397) is disposed in at least one stepped space between a plurality of layers of each of the first sealing portion and the second sealing portion of the FPCB.

2. The electronic device of claim 1, further comprising:

a first sealing member(380a) for sealing the first opening(331a); and

a second sealing member(380b) for sealing the second opening(332a),

wherein a surface of the first sealing portion(3900a) is compressed by the first sealing member(380a), and

wherein a surface of the second sealing portion(3900b) is compressed by the second sealing member(380b).

3. The electronic device of any one of claim 1 to 2, wherein the FPCB including plurality of substrates stacked in a stacking direction, and

the plurality of substrates(391;392;393;394) each comprise:

a base layer(3911);

a metal layer(3912) stacked on one surface of the base layer(3911), and forming an uneven surface; and

a dielectric layer(3914) stacked to cover the metal layer(3912),

wherein a stepped space(396) by the uneven surface is formed between the plurality of substrates, and

wherein the waterproof member(397) is disposed in the stepped space(396).

4. The electronic device of any one of claim 1 to 3,

wherein a pair of adjacent substrates(492;493) among the plurality of substrates are stacked such that respective uneven surfaces thereof face each other, and

wherein the waterproof member(497c) is disposed between the facing uneven surfaces of the pair of adjacent substrates.

5. The electronic device of any one of claim 1 to 4, wherein, based on a cross section parallel to the stacking direction, the facing uneven surfaces of the pair of adjacent substrates(492;493) are formed to have mutually matching cross sections such that the stepped space(496) is formed therebetween.

6. The electronic device of any one of claim 1 to 4, wherein, based on a cross section parallel to the stacking direction, the facing uneven surfaces of the pair of adjacent substrates(492;493) are formed such that the respective metal patterns thereof do not overlap each other.

7. The electronic device of any one of claim 1 to 3,

wherein the plurality of substrates(491;492;493;494), based on a cross section parallel to the stacking direction, comprise:

a first substrate(491) comprising a first base layer(4911) and a first metal layer(4912) stacked on the first base(4911) layer and forming a first uneven surface;

a second substrate(492) comprising a second base layer(4921) stacked on the first base layer(4911), and a second metal layer(4922) stacked on the second base layer(4921) and forming a second uneven surface in a direction opposite to the first uneven surface;

a third substrate(493) comprising a third base layer(4931) and a third metal layer(4932) stacked on the third base(4931) layer and forming a third uneven surface in a direction facing the second uneven surface; and

a fourth substrate(494) comprising a fourth base layer(4941) stacked on the third base layer(4931), and a fourth metal layer(4942) stacked on the fourth base layer(4941) and forming a fourth uneven surface in a direction opposite to the third uneven surface, and

wherein the waterproof member(497c) is disposed between the second uneven surface and the third uneven surface.

8. The electronic device of any one of claim 1 to 3,

wherein the plurality of substrates(391;392;393;394), based on a cross section parallel to the stacking direction. comprise:

a first substrate(391) comprising a first base layer(3911) and a first metal layer(3912) stacked on the first base layer(3911) and forming a first uneven surface;

a second substrate(392) comprising a second base layer(3921), and a second metal layer stacked on the second base(3921) layer and forming a second uneven surface in a direction facing the first base layer(3911);

a third substrate(393) comprising a third base(3931) layer facing the second base layer(3921), and a third metal layer(3932) stacked on the third base

layer(3931) and forming a third uneven surface in a direction opposite to the second uneven surface; and

a fourth substrate(394) comprising a fourth base layer(3941), and a fourth metal layer(3942) stacked on the fourth base layer(3941) and forming a fourth uneven surface in a direction opposite to the third uneven surface, and

wherein a first waterproof member(3971b) is disposed between the first base layer(3911) and the second uneven surface, and a second waterproof member(3972b) is disposed between the fourth base layer(3941) and the third uneven surface.

9. The electronic device of any one of claim 1 to 8,

wherein the FPCB(290;390) comprises:

a first flexible portion(3903a) to be bent to an outer side of the first opening(331a) from the first sealing portion(3900a) toward the hinge structure(334); and

a second flexible portion(3903b) to be bent to an outer side of the second opening(332a) from the second sealing portion(3900b) toward the hinge structure(334), and

wherein the waterproof member is omitted from the first flexible portion(3903a) and the second flexible portion(3903b).

10. The electronic device of any one of claim 1 to 9,

wherein the FPCB(290;390) comprises:

a first extension portion(3904a) to be bent to the outer side of the first opening(331a) from the first sealing portion(3900a) toward the first space(310a); and

a second extension portion(3904b) to be bent to the outer side of the second opening(332a) from the second sealing portion(3900b) toward the second space(320a), and

wherein the waterproof member is omitted from the first extension portion(3904a) and the second extension portion(3904b).

11. The electronic device of any one of claim 1 to 10,

wherein a stepped space(696a) by the uneven surfaces is formed between the plurality of substrates(691;692), and

wherein a ratio of an area of the stepped space to a length of the first sealing portion(3900a) and the second sealing portion(3900b) in the extending direction is less than a ratio of an area of the stepped space to a length of the first flexible portion(3903a) and the second flexible portion(3903b) in the extending direction.

12. The electronic device of any one of claim 1 to 11,

wherein a stepped space(696b) by the uneven surfaces is formed between the plurality of substrates, and

wherein based on a state in which the stepped space(696b) is viewed in the stacking direction, the stepped space forms a meander pattern in the first sealing portion(3900a) or the second sealing portion(3900b).

13. The electronic device of any one of claim 1 to 12,

wherein a stepped space by the uneven surfaces is formed between the plurality of substrates, and

wherein based on a state in which the stepped space is viewed in the stacking direction, the metal patterns comprise one or more stub shapes protruding toward the inside of the stepped space, in the first sealing portion(3900a) or the second sealing portion(3900b).

14. The electronic device of any one of claim 1 to 13,

wherein a stepped space(796a) by the uneven surface is formed between the plurality of substrates, and

wherein based on a state in which the stepped space(796a) is viewed in the stacking direction, the metal patterns comprise one or more dummy patterns formed to be positioned inside the stepped space(796a), in the first sealing portion(3900a) or the second sealing portion(3900b).

15. The electronic device of any one of claim 1 to 14, wherein the waterproof member(397) is formed between the plurality of substrates or is an elastic sheet inserted between the plurality of substrates.